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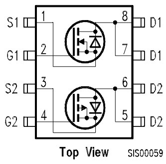
SIPMOS® Small-Signal-Transistor

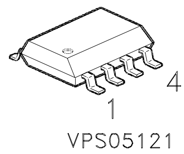
Features

- Dual N- and P -Channel
- Enhancement mode
- Logic Level
- Avalanche rated
- d*v*/d*t* rated

Product Summary

		N	P	
Drain source voltage	V_{DS}	20	-20	V
Drain-Source on-state resistance	$R_{DS(on)}$	0.1	0.1	Ω
Continuous drain current	I_D	3.7	-3.7	A





Type	Package	Ordering Code
BSO 215 C	SO 8	Q67041-S4025

Maximum Ratings,at T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Value		Unit
		N	P	
Continuous drain current	I_D			A
T_A = 25 °C		3.7	-3.7	
T_A = 70 °C		3	-3	
Pulsed drain current	$I_{D\ puls}$	14.8	-14.8	
T_A = 25 °C				
Avalanche energy, single pulse	E_{AS}			mJ
I_D = 3 A, V_{DD} = 15 V, R_{GS} = 25 Ω		26	-	
I_D = -3.7 A , V_{DD} = -15 V, R_{GS} = 25 Ω		-	68	
Avalanche energy, periodic limited by T_{jmax}	E_{AR}	0.2	0.2	
Reverse diode d*v*/d*t*, T_{jmax} = 150 °C	d*v*/d*t*			kV/µs
I_S = 3 A, V_{DS} = 16 V, d*i*/d*t* = 200 A/µs		6	-	
I_S = -2.7 A, V_{DS} = -16 V, d*i*/d*t* = -200 A/µs		-	6	
Gate source voltage	V_{GS}	±20	±20	V
Power dissipation	P_{tot}	2	2	W
T_A = 25 °C				
Operating and storage temperature	T_j , T_{stg}	-55...+150		°C
IEC climatic category; DIN IEC 68-1		55/150/56		

Termal Characteristics

Parameter		Symbol	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Thermal resistance, junction - soldering point	N	R_{thJS}	-	-	40	K/W
	P		-	-	40	
SMD version, device on PCB:		R_{thJA}				
@ min. footprint; t ≤ 10 sec.	N		-	-	110	
@ 6 cm^2 cooling area [1]); t ≤ 10 sec.	N		-	-	62.5	
@ min. footprint; t ≤ 10 sec.	P		-	-	100	
@ 6 cm^2 cooling area [1]); t ≤ 10 sec.	P		-	-	62.5	

Static Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter		Symbol	min.	typ.	max.	Unit
Drain- source breakdown voltage		$V_{(BR)DSS}$				V
V_{GS} = 0 V, I_D = 250 µA	N		20	-	-	
V_{GS} = 0 V, I_D = -250 µA	P		-20	-	-	
Gate threshold voltage, $V_{GS} = V_{DS}$		$V_{GS(th)}$				
I_D = 10 µA	N		1.2	1.5	2	
I_D = -450 µA	P		-1	-1.5	-2	
Zero gate voltage drain current		I_{DSS}				µA
V_{DS} = 20 V, V_{GS} = 0 V, T_j = 25 °C	N		-	0.1	1	
V_{DS} = 20 V, V_{GS} = 0 V, T_j = 125 °C	N		-	10	100	
V_{DS} = -20 V, V_{GS} = 0 V, T_j = 25 °C	P		-	-0.1	-1	
V_{DS} = -20 V, V_{GS} = 0 V, T_j = 125 °C	P		-	-10	-100	
Gate-source leakage current		I_{GSS}				nA
V_{GS} = 20 V, V_{DS} = 0 V	N		-	10	100	
V_{GS} = -20 V, V_{DS} = 0 V	P		-	-10	-100	
Drain-Source on-state resistance		$R_{DS(on)}$				Ω
V_{GS} = 4.5 V, I_D = 3 A	N		-	0.1	0.15	
V_{GS} = -4.5 V, I_D = -3 A	P		-	0.1	0.15	
Drain-Source on-state resistance		$R_{DS(on)}$				Ω
V_{GS} = 10 V, I_D = 3.7 A	N		-	0.05	0.1	
V_{GS} = -10 V , I_D = -3.7 A	P		-	0.06	0.1	

[1]Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm [2] (one layer, 70 µm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

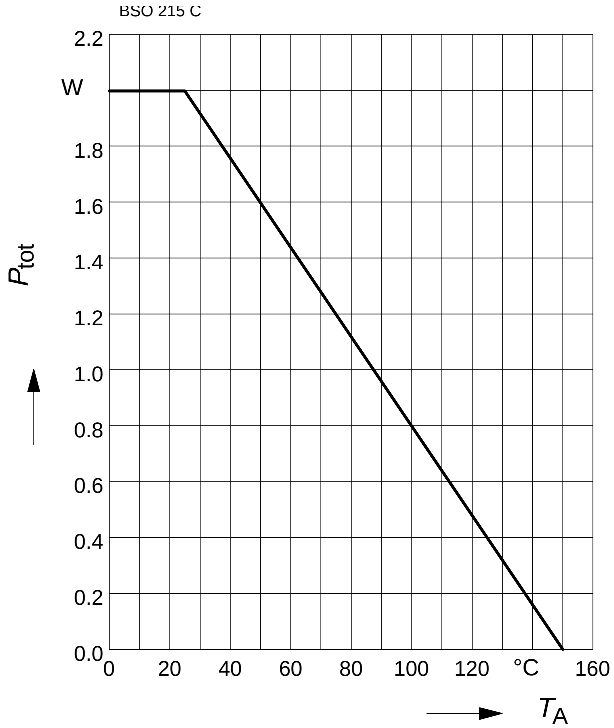
Parameter		Symbol	Values			Unit
			min.	typ.	max.	
Characteristics						
Transconductance		g_{fs}				S
$V_{DS} \geq 2 * I_D * R_{DS(on)max}$, I_D = 3 A	N		2.1	4.4	-	
$VV_{DS} \geq 2 * I_D * R_{DS(on)max}$, I_D = -3 A	P		2.6	5.2	-	
Input capacitance		C_{iss}				pF
V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	N		-	197	246	
V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz	P		-	380	475	
Output capacitance		C_{oss}				
V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	N		-	109	136	
V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz	P		-	290	360	
Reverse transfer capacitance		C_{rss}				
V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz	N		-	59	74	
V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz	P		-	103	128	
Turn-on delay time		$t_{d(on)}$				ns
V_{DD} = 10 V, V_{GS} = 4.5 V, I_D = 3 A, R_G = 33 Ω	N		-	15	22.5	
V_{DD} = -10 , V_{GS} = -4.5 V, I_D = -3 A, R_G = 13 Ω	P		-	24	36	
Rise time		t_r				
V_{DD} = 10 V, V_{GS} = 4.5 V, I_D = 3 A, R_G = 33 Ω	N		-	88	132	
V_{DD} = -10 , V_{GS} = -4.5 V, I_D = -3 A, R_G = 13 Ω	P		-	236	354	
Turn-off delay time		$t_{d(off)}$				
V_{DD} = 10 V, V_{GS} = 4.5 V, I_D = 3 A, R_G = 33 Ω	N		-	12.3	18.5	
V_{DD} = -10 , V_{GS} = -4.5 V, I_D = -3 A, R_G = 13 Ω	P		-	87	130	
Fall time		t_f				
V_{DD} = 10 V, V_{GS} = 4.5 V, I_D = 3 A, R_G = 33 Ω	N		-	17.1	25.7	
V_{DD} = -10 V, V_{GS} = -4.5 V, I_D = -3 A, R_G = 13 Ω	P		-	168	252	

Electrical Characteristics, at T_j = 25 °C, unless otherwise specified

Parameter		Symbol	Values min.	Values typ.	Values max.	Unit
Characteristics						
Gate to source charge		Q_{gs}				nC
V_{DD} = 16 , I_D = 3.7 A	N		-	1.3	2	
V_{DD} = -16 , I_D = -3.7 A	P		-	1.9	2.9	
Gate to drain charge		Q_{gd}				
V_{DD} = 16 , I_D = 3.7 A	N		-	3	4.5	
V_{DD} = -16 , I_D = -3.7 A	P		-	4.4	6.6	
Gate charge total		Q_g				
V_{DD} = 16 , I_D = 3.7 A, V_{GS} = 0 to 10V	N		-	7.7	11.5	
V_{DD} = -16 , I_D = -3.7 A, V_{GS} = 0 to -10V	P		-	13.2	19.8	
Gate plateau voltage		$V_{(plateau)}$				V
V_{DD} = 16 , I_D = 3.7 A	N		-	3.5	-	
V_{DD} = -16 , I_D = -3.7 A	P		-	2.8	-	
Reverse Diode						
Inverse diode continuous forward current	N	I_S	-	-	3.7	A
T_A = 25 °C	P		-	-	-3.7	
Inverse diode direct current,pulsed	N	I_{SM}	-	-	14.8	
T_A = 25 °C	P		-	-	-14.8	
Inverse diode forward voltage		V_{SD}				V
V_{GS} = 0 V, I_F = I_S	N		-	0.84	1.1	
V_{GS} = 0 V, I_F = I_S	P		-	-0.82	-1	
Reverse recovery time		t_{rr}				ns
V_R = 10 V, I_F=I_S, di_F/dt = 100 A/µs	N		-	46.5	70	
V_R = -10 V, I_F=I_S , di_F/dt = -100 A/µs	P		-	137	205	
Reverse recovery charge		Q_{rr}				µC
V_R = 10 V, I_F=I_S , di_F/dt = 100 A/µs	N		-	18.4	27.6	
V_R = -10 V, I_F=I_S, di_F/dt = -100 A/µs	P		-	80	120	

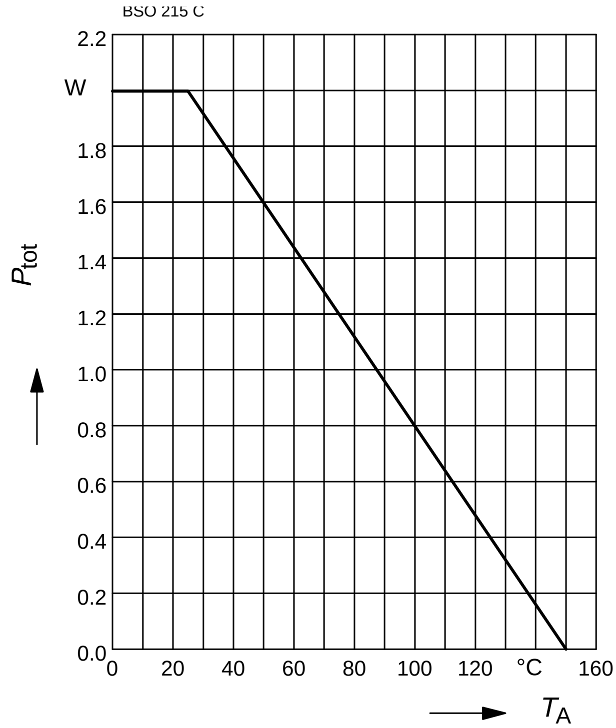
Power Dissipation (N-Ch.)

$P_{tot} = f(T_A)$



Power Dissipation (P-Ch.)

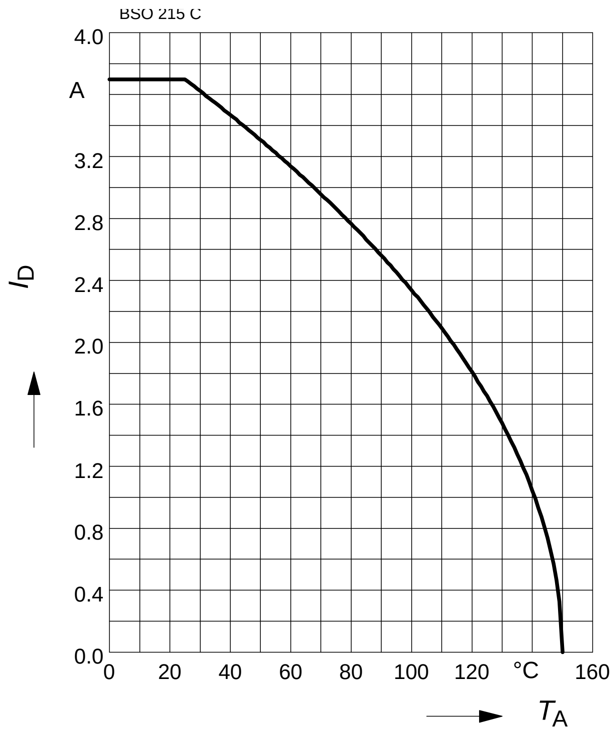
$P_{tot} = f(T_A)$



Drain current (N-Ch.)

$I_D = f(T_A)$

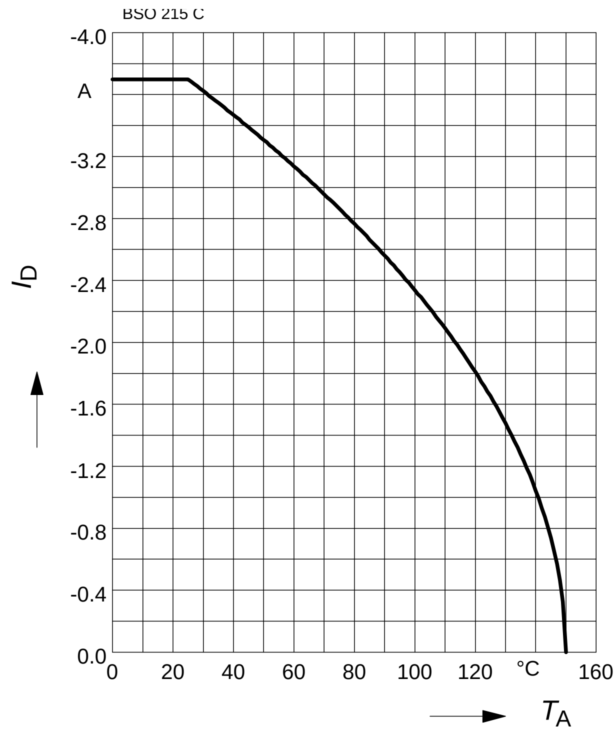
parameter: $V_{GS} \geq 10$ V



Drain current (P-Ch.)

$I_D = f(T_A)$

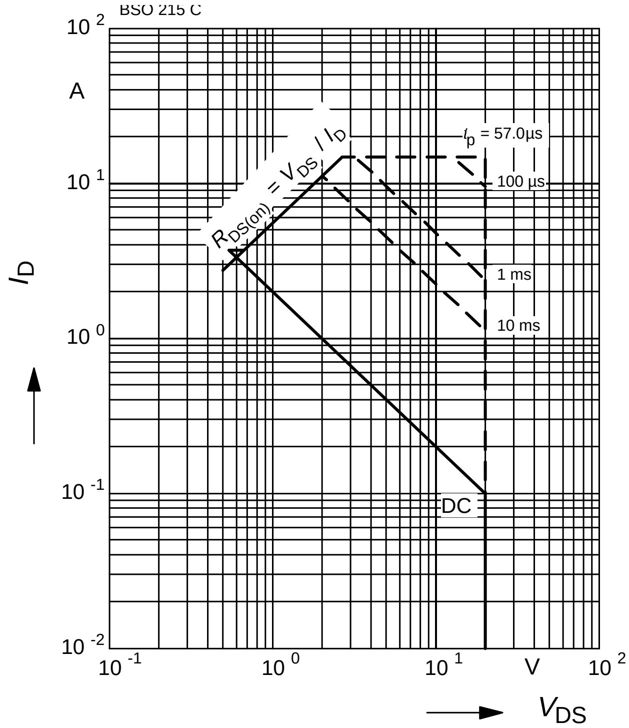
parameter: $V_{GS} \geq -10$ V



Safe operating area (N-Ch.)

$I_D = f(V_{DS})$

parameter : $D = 0$, $T_A = 25$ °C



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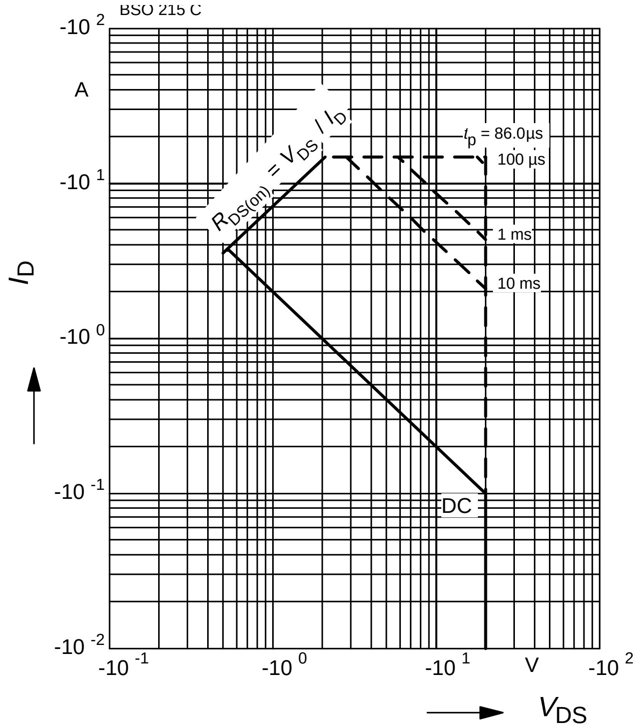
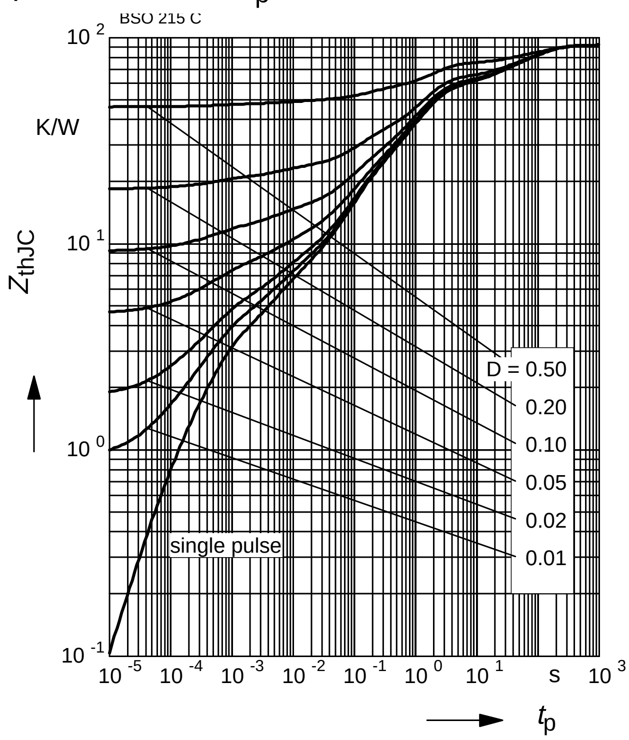
parameter : $D = 0$, $T_A = 25$ °C



Transient thermal impedance (N-Ch.)

$Z_{thJC} = f(t_p)$

parameter : $D = t_p / T$



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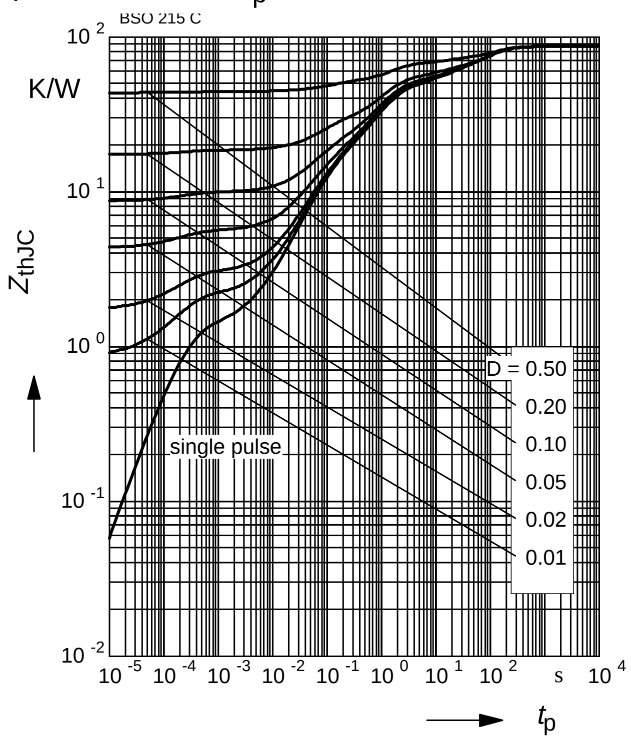
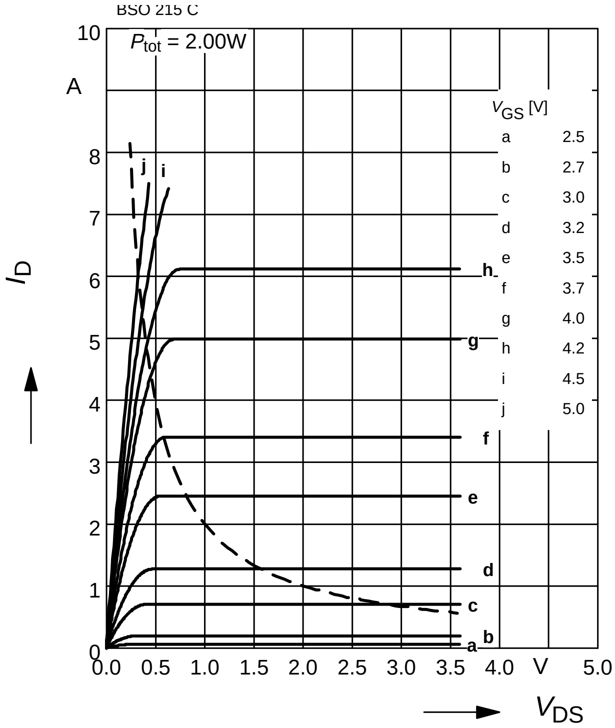


Typ. output characteristics (N-Ch.)

$I_D = f(V_{DS})$

parameter: t_p = 80 µs



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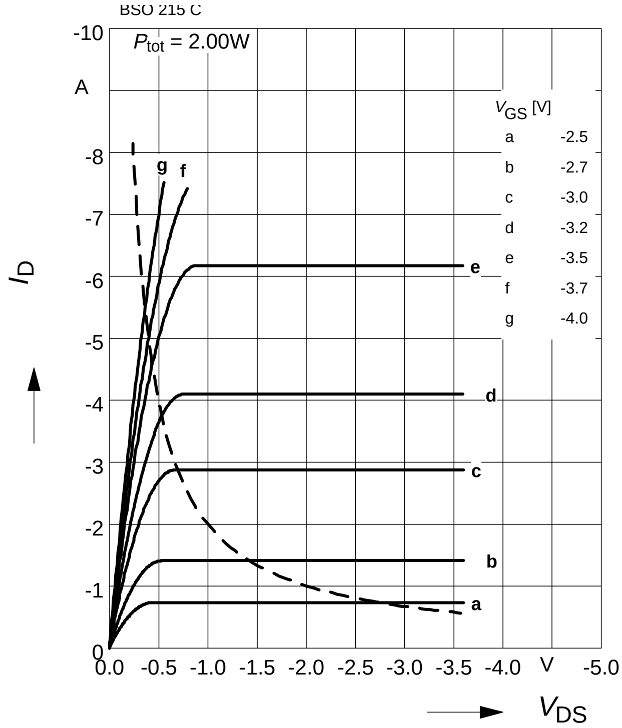
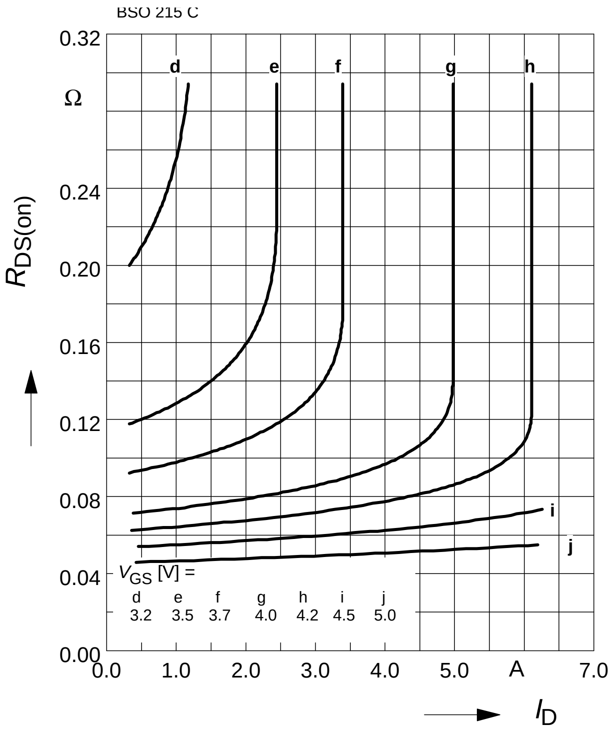
parameter: t_p = 80 µs



Typ. drain-source-on-resistance (N-Ch.)

$R_{DS(on)} = f(I_D)$

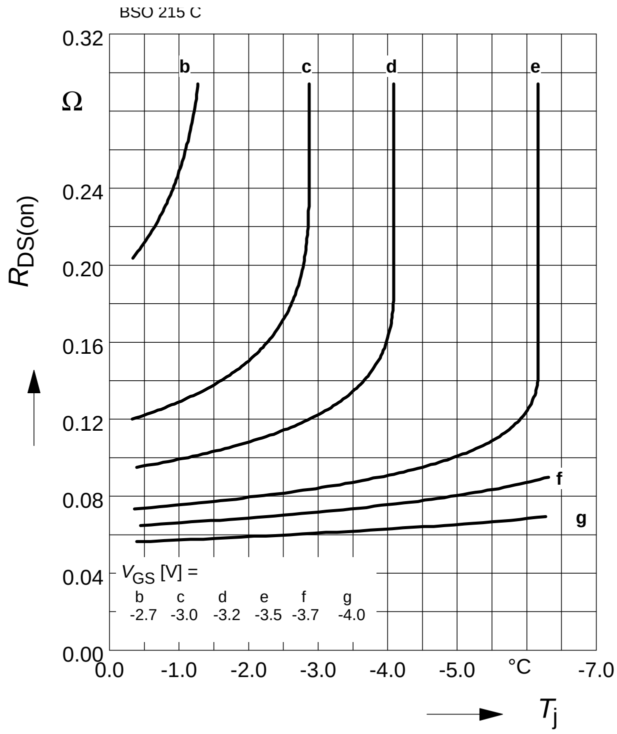
parameter: V_{GS}



Typ. drain-source-on-resistance (P-Ch.)

$R_{DS(on)} = f(I_D)$

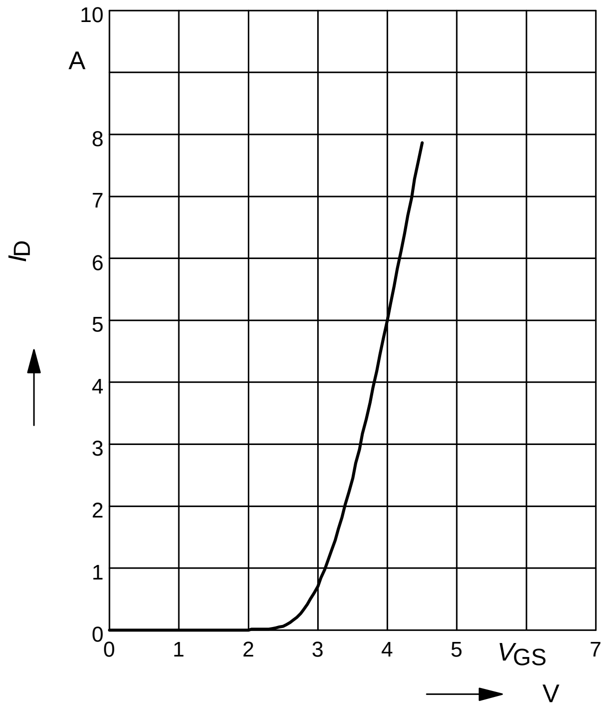
parameter: V_{GS}



Typ. transfer characteristics (N-Ch.)

parameter: t_p = 80 µs

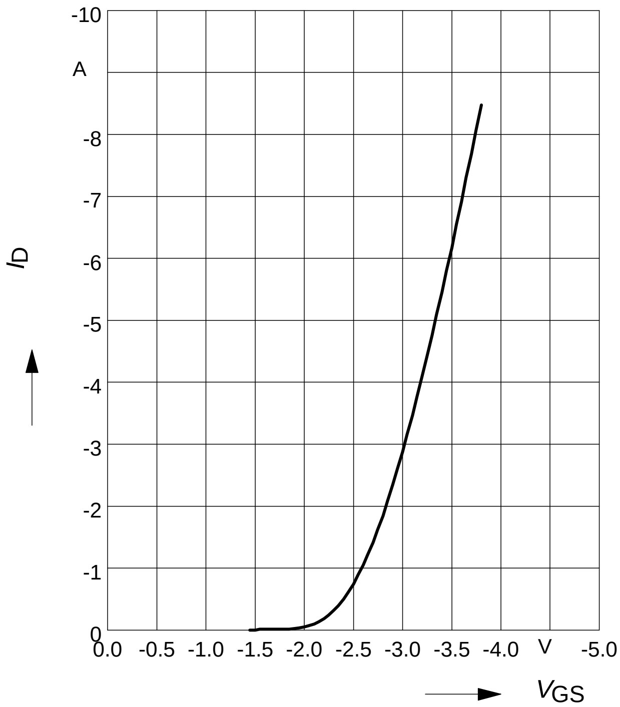
$I_D = f(V_{GS})$, $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



Typ. transfer characteristics (P-Ch.)

parameter: t_p = 80 µs

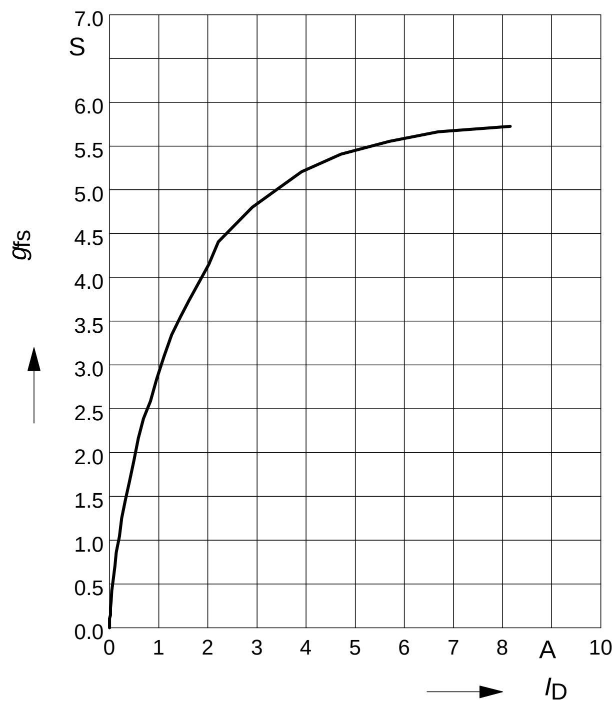
$I_D = f(V_{GS})$, $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



Typ. forward transconductance (N-Ch.)

$g_{fs} = f(I_D)$; T_j = 25 °C

parameter: g_{fs}



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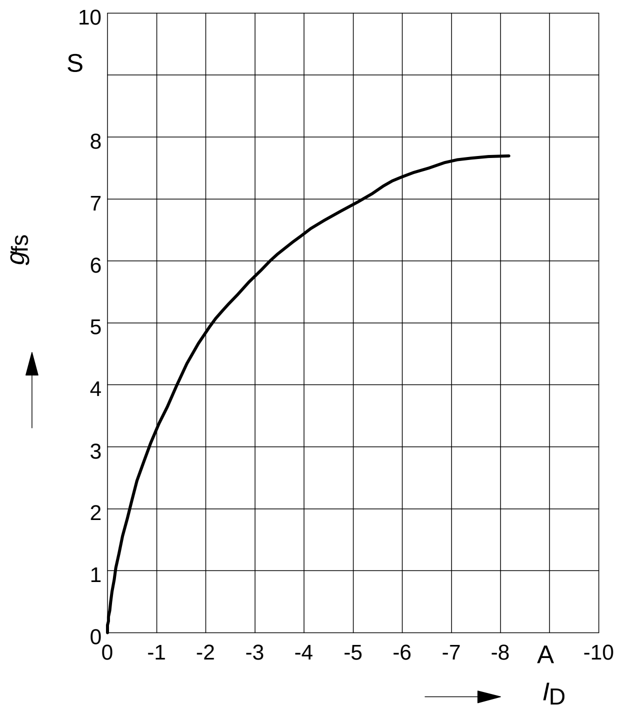
$g_{fs} = f(I_D)$; T_j = 25 °C

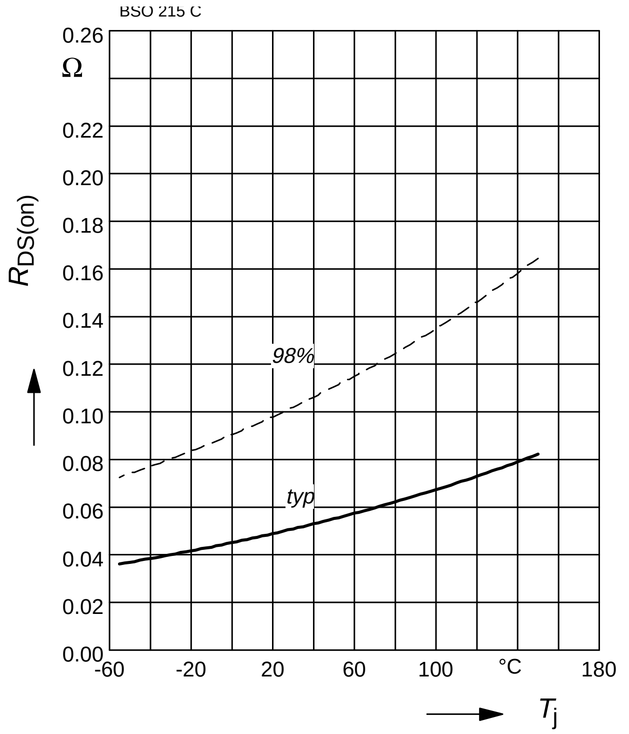
parameter: g_{fs}



Drain-source on-resistance (N-Ch.)

$R_{DS(on)} = f\ (T_j)$

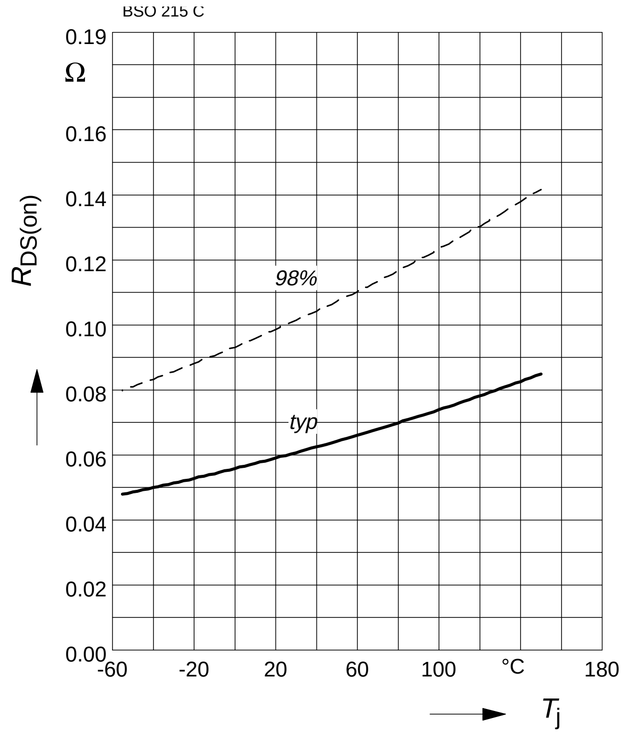
parameter : I_D = 3.7 A , V_{GS} = 10 V



Drain-source on-resistance (P-Ch.)

$R_{DS(on)} = f\ (T_j)$

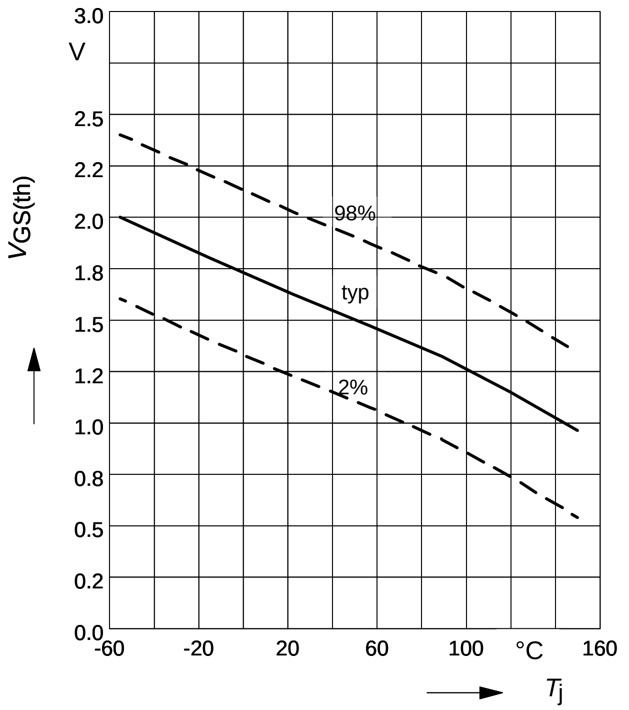
parameter : I_D = -3.7 A , V_{GS} = -10 V



Gate threshold voltage (N-Ch.)

$V_{GS(th)} = f\ (T_j)$

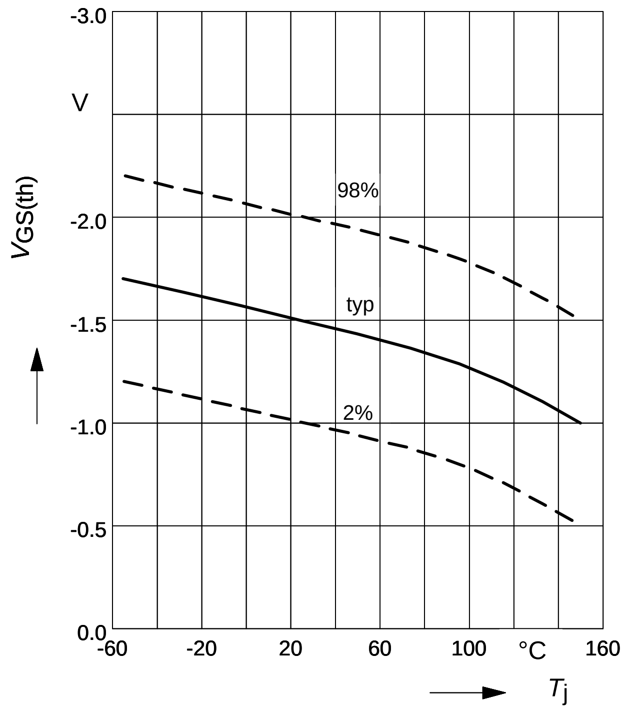
parameter: $V_{GS} = V_{DS}$, I_D = 10 µA



Gate threshold voltage (P-Ch.)

$V_{GS(th)} = f\ (T_j)$

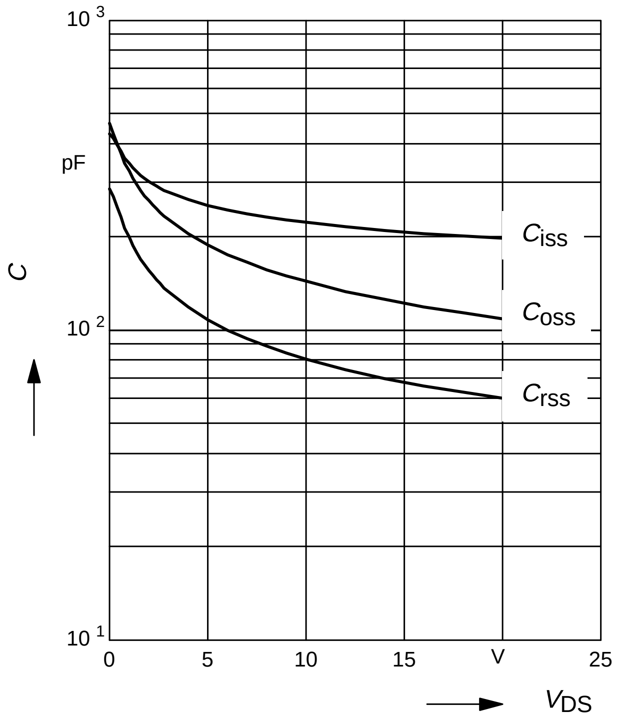
parameter: $V_{GS} = V_{DS}$, I_D = -450 µA



Typ. capacitances (N-Ch.)

$C = f(V_{DS})$

parameter: V_{GS}=0 V, f=1 MHz



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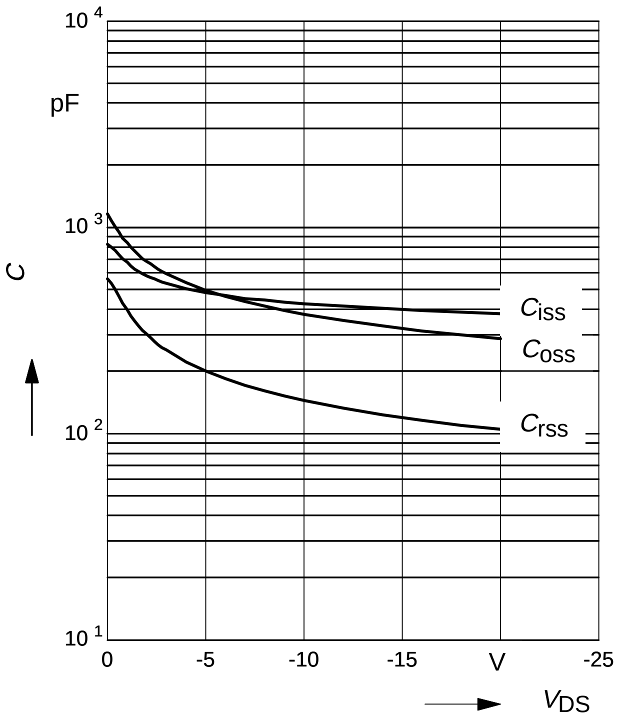
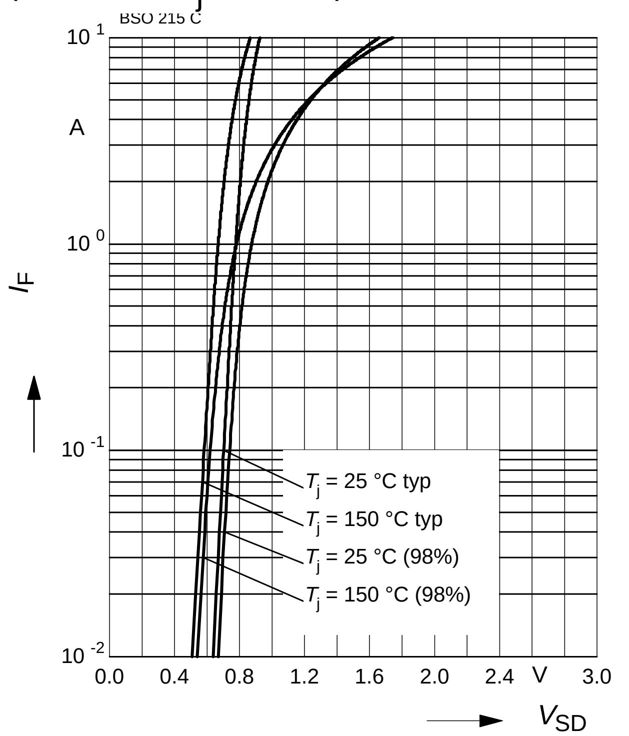


Forward characteristics of reverse diode

$I_F = f(V_{SD})$, (N-Ch.)

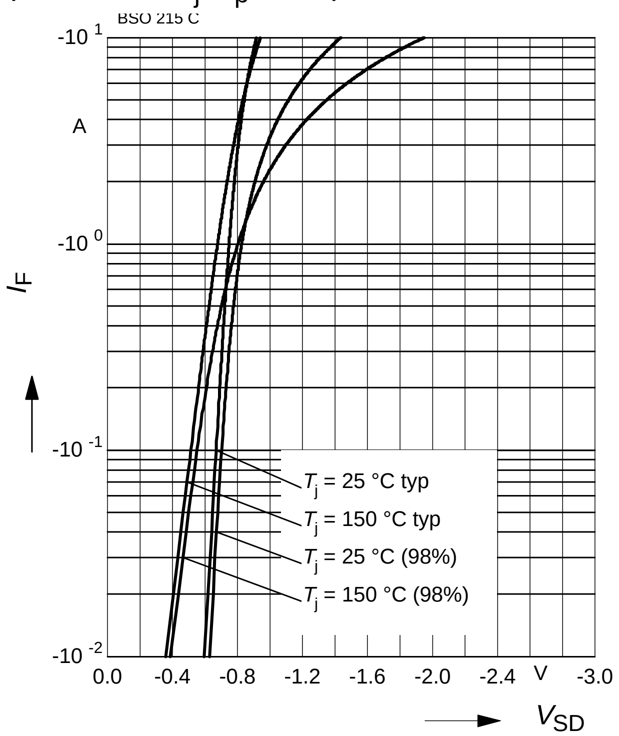
parameter: T_j , t_p = 80 µs



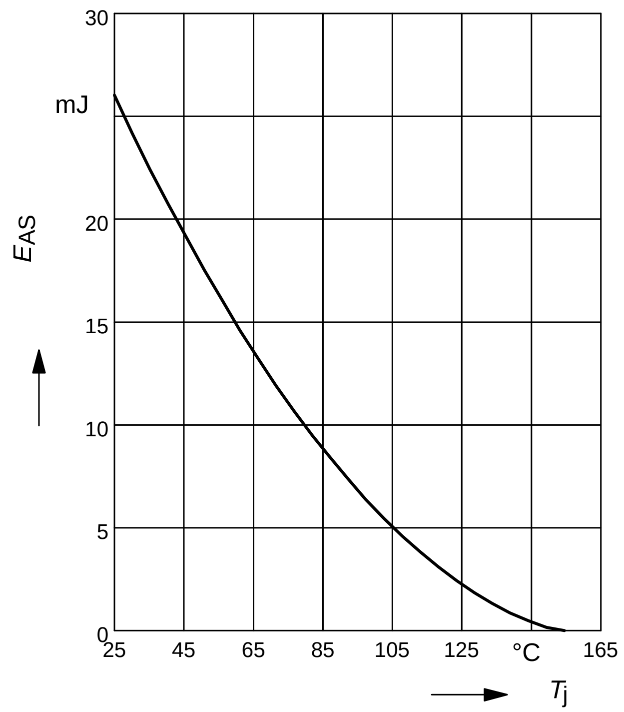
Forward characteristics of reverse diode

$I_F = f(V_{SD})$, (P-Ch.)

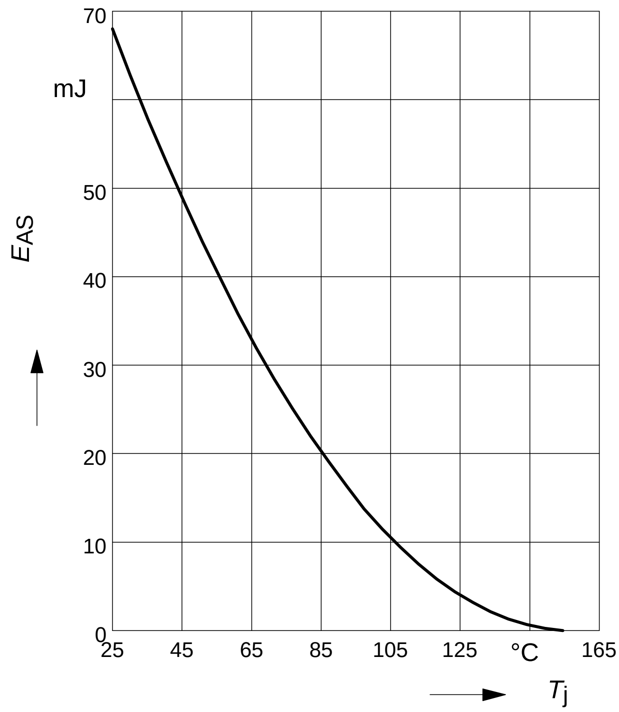
parameter: T_j , t_p = 80 µs



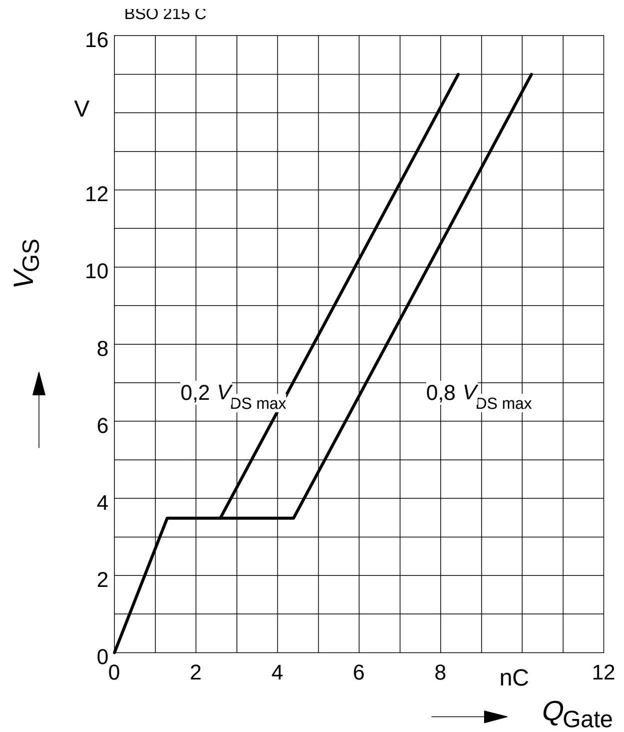
Avalanche Energy $E_{AS} = f(T_j)$ (N-Ch.)
parameter: I_D = 3 A, V_{DD} = 15 V
R_{GS} = 25 Ω



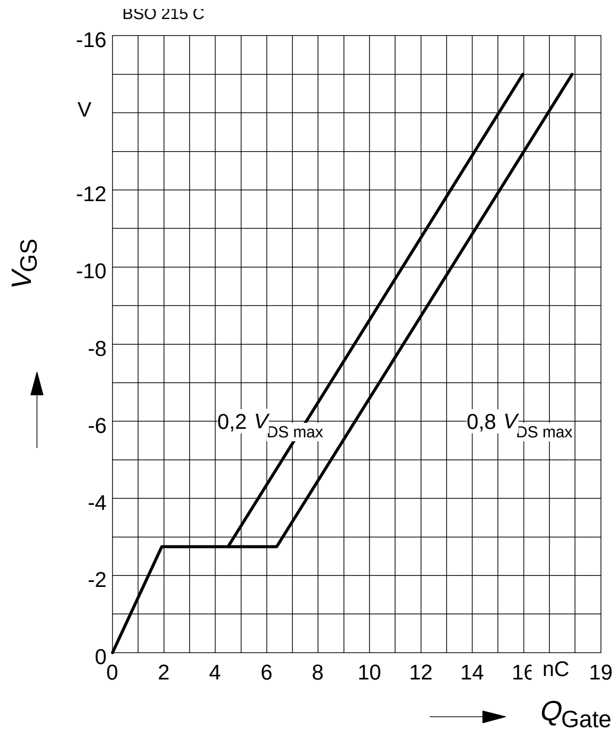
Avalanche Energy $E_{AS} = f(T_j)$
parameter: I_D = -3.7 A , V_{DD} = -15 V
R_{GS} = 25 Ω



Typ. gate charge (N-Ch.)
V_{GS} = f (Q_{Gate})
parameter: I_D = 3.7 A

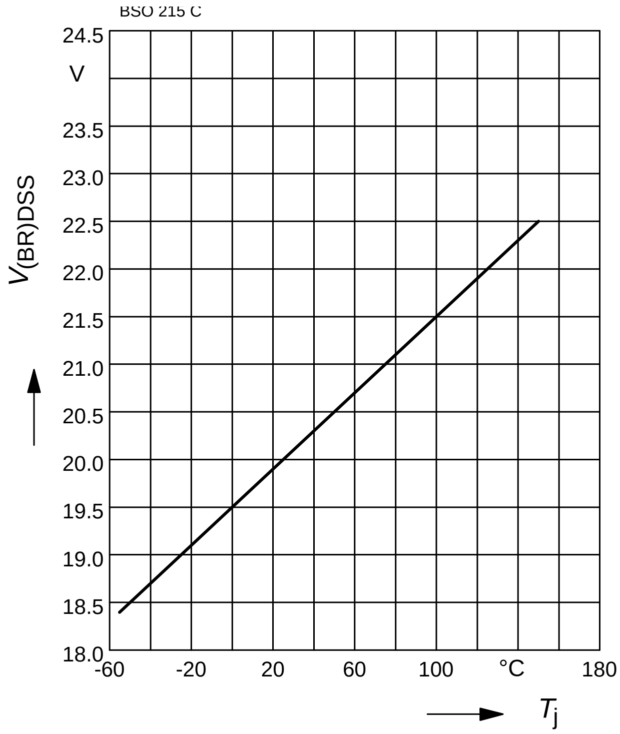


Typ. gate charge (P-Ch.)
V_{GS} = f (Q_{Gate})
parameter: I_D = -3.7 A



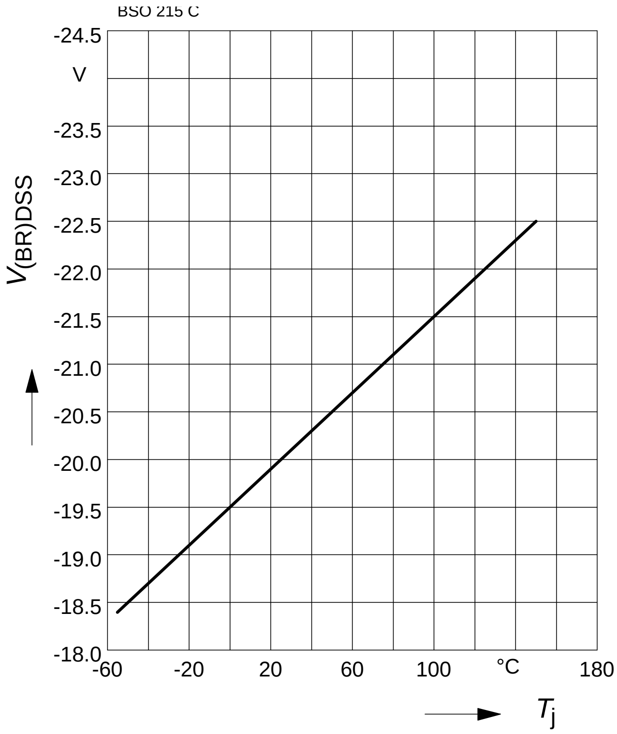
Drain-source breakdown voltage

$V_{(BR)DSS} = f\ (T_j)$, (N-Ch.)



Drain-source breakdown voltage

$V_{(BR)DSS} = f\ (T_j)$



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